

Notice of References Cited

Application N.

09/208962

Applicant(s)

Elco

Examiner

Abrams

Group Art Unit

2839

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☆	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS
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V	Sized Solder Bumps make solid joints, Electronics, page 46	11-1981
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* A copy of this reference is not being furnished with this Office action.
(See Manual of Patent Examining Procedure, Section 707.05(a).)